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(Re $\mathbf{D}_{\mathbf{I}}$ **PATENTS ONLY** 103383604 Ademark Office: Please record the attached documents or the new address(es) below. 1. Name of Conveying Party(ies) 2. Name and address of receiving party(ies) Hiroyuki YAMASHITA, Mamoru KOBAYASHI, Eiji IMAI, Name: HITACHI HIGH-TECHNOLOGIES Yoshio MORISHIGE, Koichi NAGOYA, Hideki FUKUSHIMA CORPORATION Additional name(s) of conveying party(ies) attached? Tyes No. 3. Nature of Conveyance/Execution Date(s) Address: 24-14, Nishishinbashi 1-chome, Minato-ku Execution February 9, 2007, February 9, 2007, February Tokyo, JAPAN 9, 2007, February 9, 2007, February 9, 2007, Date(s): February 8, 2007 (respectively) **⊠** Assignment ☐ Merger Security Agreement Change of Name ☐ Joint Research Agreement Government Interest Assignment Executive Order 9424, Confrmatory License Additional name(s) & address(es) attached? Yes No Other 4. Application or patent number(s): This document is being filed together with a new application A. Patent Application No(s). B. Patent No(s). Additional numbers attached? Yes No 5. Name and address to whom correspondence concerning 6. Total number of applications and patents document should be mailed: involved: Name: MCDERMOTT WILL & EMERY LLP 7. Total fee (37 CFR 1.21(h) & 3.41) \$40.00 Internal Address: Authorized to be charged by credit card Authorized to be charged to deposit account Enclosed Street Address: 600 13th Street, N.W. None required (government interest not affecting title)nt City: Washington State: D.C. 20005-3096 8. Payment Information: Phone Number: 202.756.8000 202.756.8087 Fax Number: Credit Card Last 4 Numbers Email Address: a. **Expiration Date** Deposit Account Number 500417 b. Authorized User Name 9. Signature. February 23, 2007 Keith E. George, 34,111 Name and Registration No. of Person Signing Total number of pages including cover sheet, attachments and documents: OMB No. 0651-0027 (exp. 6/30/2008)

PATENT

REEL: 019042 FRAME: 0948

ASSIGNMENT (譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi High-Technologies Corporation, a corporation organized under the laws of Japan, located at 24-14, Nishishinbashi 1-chome, Minato-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi High-Technologies Corporation, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

FOREIGN MATTER INSPECTION METHOD AND FOREIGN MATTER INSPECTION APPARATUS

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi High-Technologies Corporation, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to Issue said Letters Patent to said Hitachi High-Technologies Corporation.

Signed on the date(s) indicated aside signatures:

RECORDED: 02/23/2007

	INVENTOR(S)	Date Signed
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PATENT REEL: 019042 FRAME: 0949